

# **RCJ200N20** Nch 200V 20A Power MOSFET

# $V_{\text{DSS}} \\$ 200V $R_{DS(on)}$ (Max.) $130 \text{m}\Omega$

# $I_D$ ±20A $P_{D}$ 106W

### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

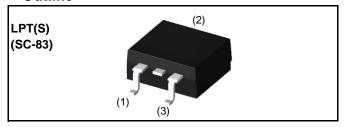
# Application

Switching Power Supply

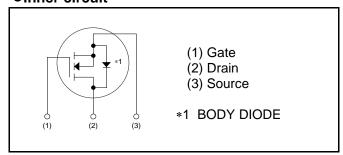
Automotive Motor Drive

Automotive Solenoid Drive

#### Outline



## ●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	24
Туре	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ200N20

# • Absolute maximum ratings $(T_a = 25^{\circ}C)$

Parameter	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	200	V	
Continuous drain current	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±20	А
	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±10.9	А
Pulsed drain current	I <sub>D,pulse</sub> *2	±80	А	
Gate - Source voltage	$V_{GSS}$	±30	V	
Avalanche energy, single pulse	E <sub>AS</sub> *3	32.3	mJ	
Avalanche current		I <sub>AR</sub> *3	10	А
Power dissipation	T <sub>c</sub> = 25°C	P <sub>D</sub>	106	W
T <sub>a</sub> = $25^{\circ}$ C <sup>*4</sup>		P <sub>D</sub>	1.56	W
Junction temperature	T <sub>j</sub>	150	°C	
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## ●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	-	1.17	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.		
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	200	-	-	V	
		$V_{DS} = 200V, V_{GS} = 0V$			25		
Zoro gato voltago drain current	la	$T_j = 25^{\circ}C$	_	-	25	μΑ	
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0V$		-	100		
		T <sub>j</sub> = 125°C					
Gate - Source leakage current	$I_{GSS}$	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	•	±100	nA	
Gate threshold voltage	$V_{GS  (th)}$	$V_{DS} = 10V$ , $I_D = 1mA$	3.0	ı	5.0	V	
		$V_{GS} = 10V, I_D = 10A$	-	100	130		
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 10A$	_	220	310	mΩ	
		T <sub>j</sub> = 125°C	_	220	310		
Forward transfer admittance	g <sub>fs</sub>	$V_{DS} = 10V, I_{D} = 10A$	4.9	9.8	-	S	

# ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
r ai ai ii e lei	Symbol Conditions —		Min.	Тур.	Max.	Offic	
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	1900	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	120	-	pF	
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	70	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 100 \text{V}, V_{GS} = 10 \text{V}$	-	35	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 10A	-	100	-	nc	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 10\Omega$	-	60	-	ns	
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	45	-		

## • Gate Charge characteristics ( $T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 100V	-	40	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 10A	-	15	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	15	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 100V, I_D = 10A$	-	8.0	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	I <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	1	20	Α
Pulsed source current	I <sub>SM</sub> *2	1 <sub>c</sub> = 23 0	-	-	80	Α
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 20A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 10A	-	100	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	350	-	nC

<sup>\*1</sup> Limited only by maximum temperature allowed.

\*5 Pulsed

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  500 $\mu$ H, V<sub>DD</sub> = 50V, Rg = 25 $\Omega$ , starting T $_{j}$  = 25°C

<sup>\*4</sup> Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve

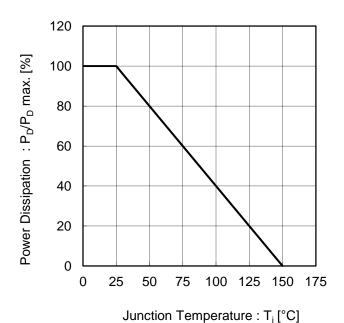
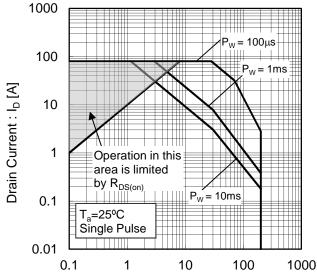
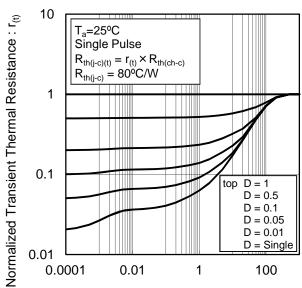


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width :  $P_W[s]$ 

Fig.4 Avalanche Current vs Inductive Load

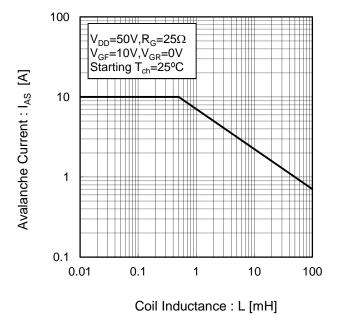
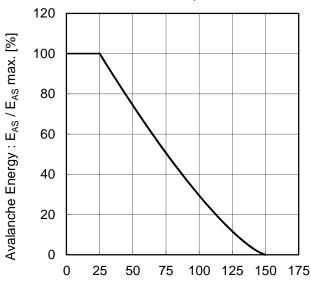
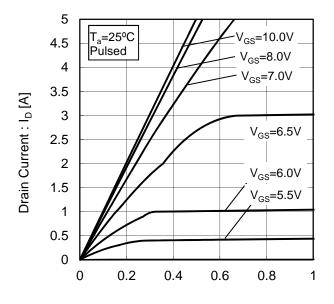


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



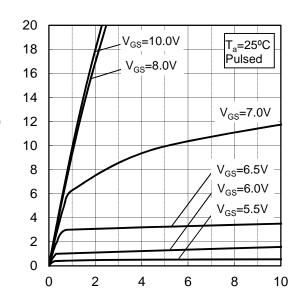
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current: I<sub>D</sub> [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage  $V_{GS} = 0V$ 270  $I_D = 1 \text{mA}$ 260 250 240 : V<sub>(BR)DSS</sub> [V] 230 220 210 200 190 180 -50 0 50 150 100 Junction Temperature : T<sub>i</sub> [°C]

100  $V_{DS} = 10V$ 10 Drain Current: I<sub>D</sub> [A] 1  $T_a = 75^{\circ}C$ T<sub>a</sub>= 25°C  $T_a = -25^{\circ}C$ 0.1 0.01 0.001 1 2 3 4 5 6 7 8 9 10 0

Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.11 Transconductance vs. Drain Current

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature 5.0  $V_{DS} = 10V$  $I_D = 1mA$ Gate Threshold Voltage: V<sub>GS(th)</sub> [V] 4.5 4.0 3.5 3.0 2.5 -50 -25 50 75 100 125 150 0 25 Junction Temperature : T<sub>i</sub> [°C]

100  $V_{DS} = 10V$ 10 Fransconductance: g<sub>fs</sub> [S] -25°C Γ<sub>a</sub>=25°C 0.1 T<sub>a</sub>=75°C =125°C 0.01 0.01 0.1 1 100 10 Drain Current : I<sub>D</sub> [A]



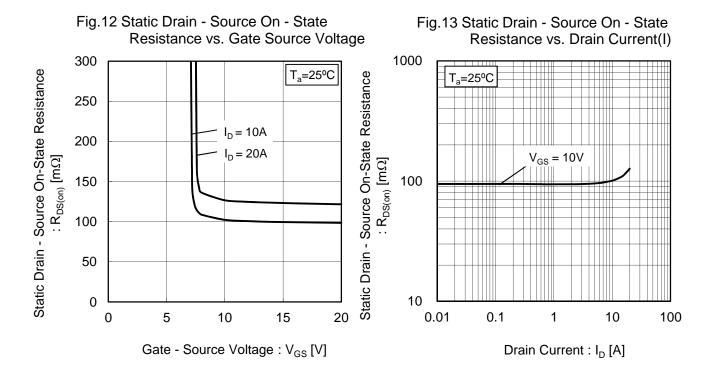
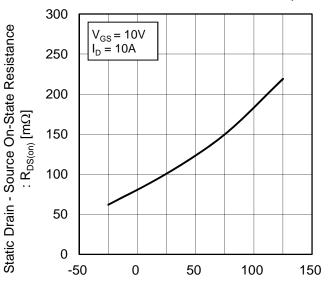


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature :  $T_j$  [°C]

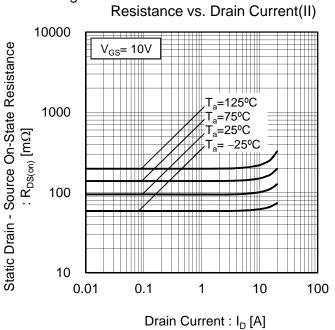


Fig.15 Static Drain - Source On - State

120
100
100
80
(%)
60
0
25 50 75 100 125 150 175

Junction Temperature : T<sub>i</sub> [°C]

Fig.16 Drain Current Derating Curve

= 0V

0.1

0.01

Fig.17 Typical Capacitance vs. Drain - Source Voltage

10000

1000  $C_{iss}$ 1000  $C_{oss}$   $C_{rss}$   $C_{rss}$ 

Drain - Source Voltage : V<sub>DS</sub> [V]

10

100

Fig.18 Switching Characteristics

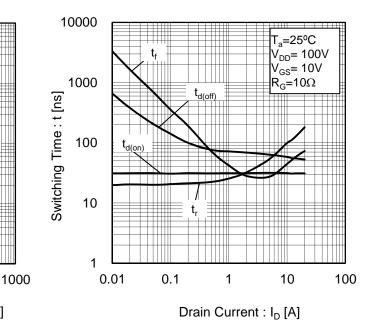
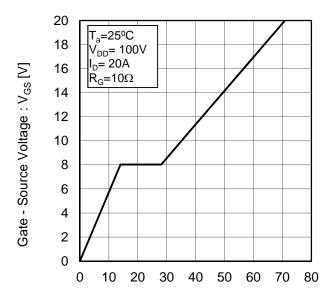
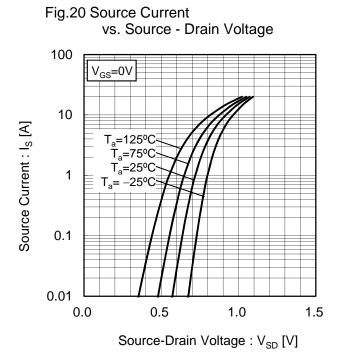
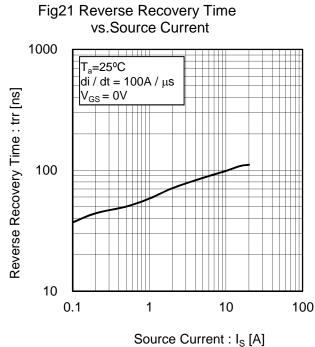


Fig.19 Dynamic Input Characteristics



Total Gate Charge :  $Q_g$  [nC]





## ●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

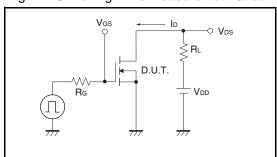


Fig.2-1 Gate Charge Measurement Circuit

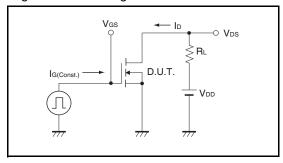


Fig.3-1 Avalanche Measurement Circuit

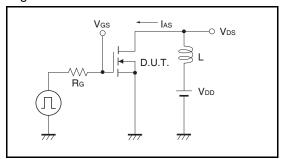


Fig.1-2 Switching Waveforms

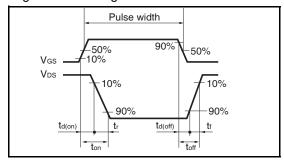


Fig.2-2 Gate Charge Waveform

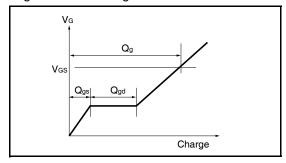
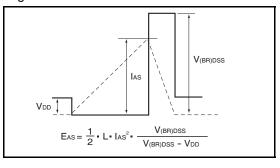
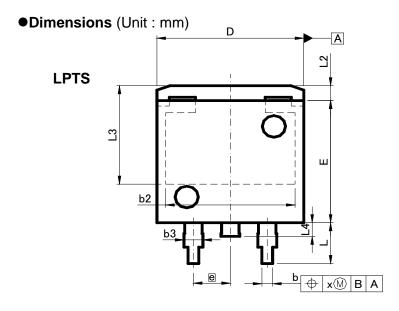
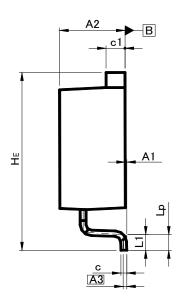
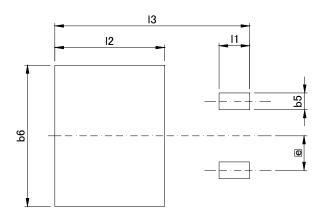


Fig.3-2 Avalanche Waveform









## Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.	10
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.043	
L3	7.	25	0.285	
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM	MILIM	ETERS	INC	HES
DIM	MIN MAX N		MIN	MAX
b5	ı	1.23	-	0.049
b6	İ	10.40	1	0.409
l1	İ	2.10	1	0.083
12	-	7.55	1	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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JÁPAN	USA	EU	CHINA
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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
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  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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